

NY-P5/NY-P5P

Extreme Low Loss & High Heat Resistance & low CTE

产品特点 FEATURES

- 01

低介电常数和低介质损耗
Low Dk 3.10@10GHz, Low Df 0.0006@10GHz
- 02

优异的电气和热可靠性
Excellent electrical and thermal reliability properties
- 03

高Tg及超低热膨胀系数
High Tg and ultra-low thermal expansion coefficiente
- 04

优异的防潮性和无铅回流焊工艺兼容
Excellent moisture resistance and lead Free reflow process compatible
- 05

优越的PTH可靠性和耐CAF能力
Superior PTH reliability and anti-CAF capability

应用领域 APPLICATIONS

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数据中心
Data Centre
- 

AI服务器
AI Server
- 

高性能计算机
High performance computing
- 

超级核心路由器和交换机
Super Core Router and Switcher

NY-P5基板典型性能 Typical Properties for NY-P5 Laminate

属性 Property	项目 Item		测试方法 IPC-TM-650	测试条件 Test Condition	单位 Unit	典型值 Typical Value	
热性能 Thermal	玻璃态转换温度 Tg Glass Transition Temperature		2.4.25	DSC	°C	\	
			2.4.24	TMA	°C	190	
			2.4.24.4	DMA	°C	200	
	X/Y轴热膨胀系数 X/Y-axis CTE		2.4.24.5	<Tg,TMA	PPM/°C	7\9	
	Z轴热膨胀系数 Z-axis CTE		2.4.24	<Tg,TMA	PPM/°C	60	
			2.4.24	>Tg,TMA	PPM/°C	210	
	热分解温度Td Decomposition Temperature		2.4.24.6	50~260°C	%	2.0	
电性能 Electrical	耐热性T288 Thermal Resistance		2.4.24.6	TGA(5%W.L)	°C	380	
	介电常数 Dk (R/C:65%) Permittivity		2.4.24.1	Clad	Min	>60	
				Etched	Min	>60	
电性能 Electrical	介电常数 Dk (R/C:65%) Permittivity	10GHz	SPDR method	C-24/23/50	—	3.10	
	介质损耗 Df (R/C:65%) Loss Tangent	10GHz	SPDR method	C-24/23/50	—	0.0007	
	体积电阻 Volume Resistivity		2.5.17.1	C-96/35/90	MΩ-cm	2.4×10 ⁹	
	表面电阻 Surface Resistivity				MΩ	1.9×10 ⁸	
物理性能 Physical	吸水率 Water Absorption		2.6.2.1	E-1/105+D-24/23	%	0.03	
	剥离强度 (HTE) Peel Strength	1oz	2.4.8	As Received	N/mm	0.65	
	剥离强度 (RTF) Peel Strength	1oz				\	
	剥离强度 (HVLP) Peel Strength	1oz				0.6	
	弯曲强度 Flexural Strength		Warp Fill	2.4.4	As Received	N/mm²	200
							175
	耐燃性 Flame Resistance			UL-94	A&E-4/125	—	V-0